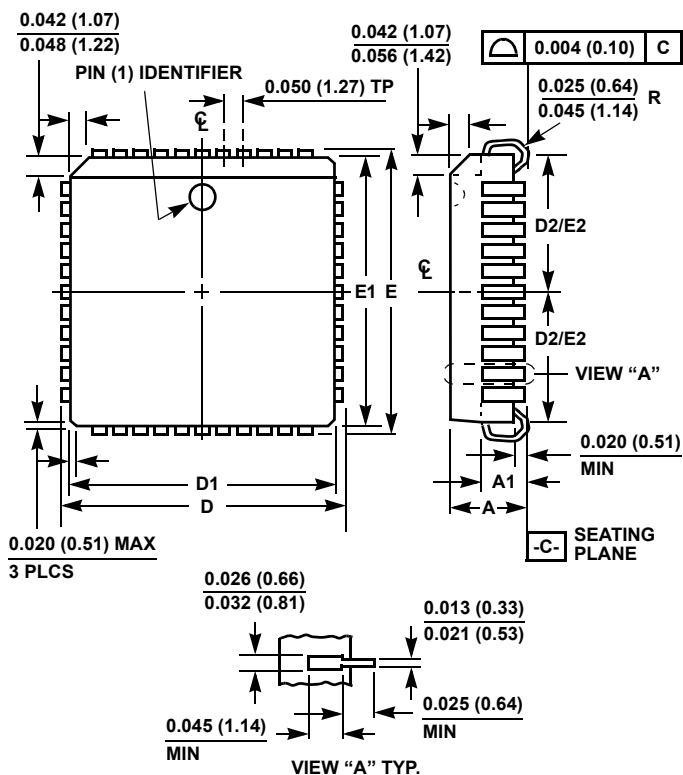


Plastic Packages for Integrated Circuits

Plastic Leaded Chip Carrier Packages (PLCC)



N84.1.15 (JEDEC MS-018AF ISSUE A) 84 LEAD PLASTIC LEADED CHIP CARRIER PACKAGE

| SYMBOL | INCHES | | MILLIMETERS | | NOTES |
|--------|--------|-------|-------------|-------|-------|
| | MIN | MAX | MIN | MAX | |
| A | 0.165 | 0.180 | 4.20 | 4.57 | - |
| A1 | 0.090 | 0.120 | 2.29 | 3.04 | - |
| D | 1.185 | 1.195 | 30.10 | 30.35 | - |
| D1 | 1.150 | 1.158 | 29.21 | 29.41 | 3 |
| D2 | 0.541 | 0.569 | 13.75 | 14.45 | 4, 5 |
| E | 1.185 | 1.195 | 30.10 | 30.35 | - |
| E1 | 1.150 | 1.158 | 29.21 | 29.41 | 3 |
| E2 | 0.541 | 0.569 | 13.75 | 14.45 | 4, 5 |
| N | 84 | | 84 | | 6 |

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NOTES:

- Controlling dimension: INCH. Converted millimeter dimensions are not necessarily exact.
- Dimensions and tolerancing per ANSI Y14.5M-1982.
- Dimensions D1 and E1 do not include mold protrusions. Allowable mold protrusion is 0.010 inch (0.25mm) per side. Dimensions D1 and E1 include mold mismatch and are measured at the extreme material condition at the body parting line.
- To be measured at seating plane -C- contact point.
- Centerline to be determined where center leads exit plastic body.
- "N" is the number of terminal positions.